

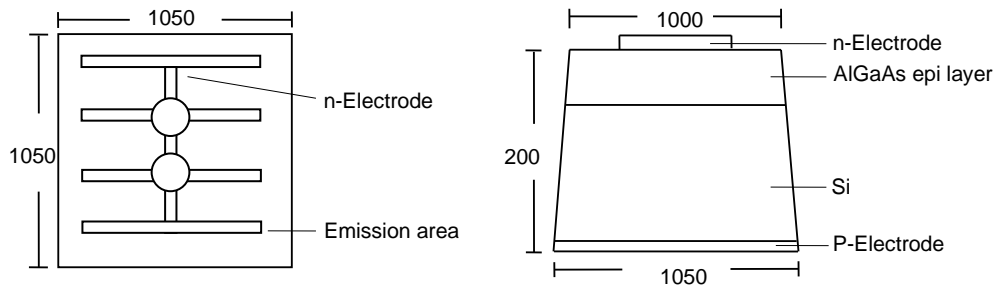
■ Features :

- Suitable for New Creative Products
- High Power
- High Performance
- Superior Thermal Stability

■ Typical Applications :

- Night Vision
- Camera
- Outdoor/Indoor applications

■ Outline Dimensions : (Unit: μm)



■ Physical Structure :

| | | |
|--------------------|---------------------|---|
| LED Chip dimension | Chip size | 1050 μm x 1050 μm |
| | Thickness | 200 \pm 25 μm |
| | Emission area | 1000 μm |
| | Bonding pad | 130 \pm 10 μm |
| Electrode | Top: N (cathode) | Gold |
| | Backside: P (anode) | Gold |

*C2

■ Electro-Optical Characteristics : ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|-----------------|-------------|------------------------|------|------|------|---------------|
| Forward Voltage | V_{FH} | $I_F = 350 \text{ mA}$ | 1.30 | - | 1.60 | V |
| Reverse Current | I_R | $V_R = 10 \text{ V}$ | - | - | 1 | μA |
| Radiant Power | P_o | $I_F = 350 \text{ mA}$ | 70 | - | 130 | mW |
| Wavelength | λ_P | $I_F = 350 \text{ mA}$ | 965 | | 985 | nm |

■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

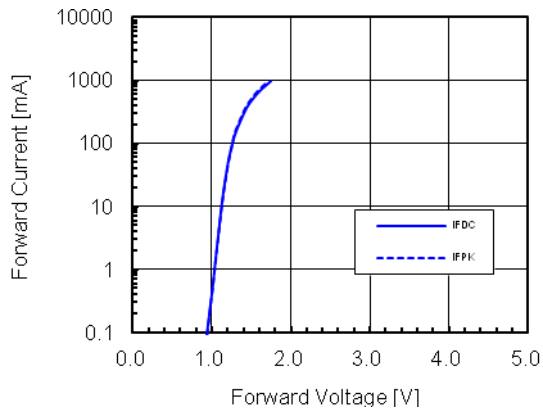


Fig 2. Relative Radiant Power vs. Wavelength

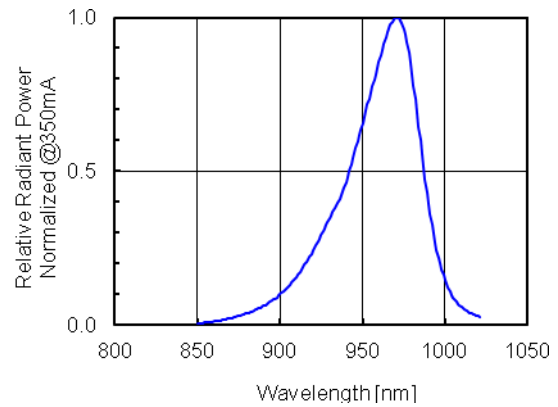


Fig 3. Relative Radiant Power vs. Forward DC Current

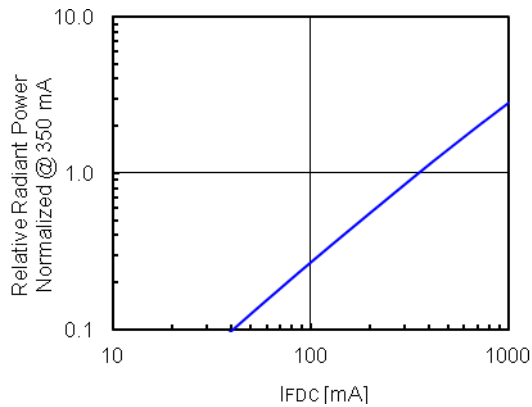


Fig 4. Relative Radiant Power vs. Forward Peak Current

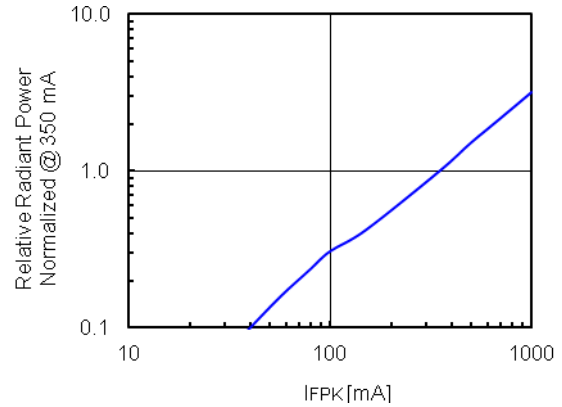


Fig 5. Forward DC Voltage vs. Temperature

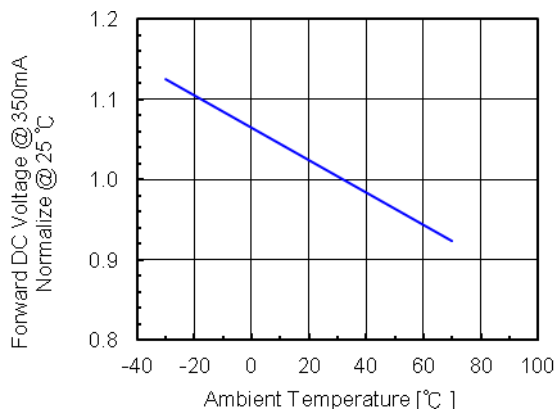


Fig 6. Relative Radiant Power vs. Temperature

